

Electronic Patent Application Fee Transmittal

Application Number:	10582881			
Filing Date:	14-Jun-2006			
Title of Invention:	Thermosetting resin composition, material for substrate and film for substrate			
First Named Inventor/Applicant Name:	Koichi Shibayama			
Filer:	Lee Cheng			
Attorney Docket Number:	MIY-0213			

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Extension - 1 month with \$0 paid	1251	1	130	130
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				130